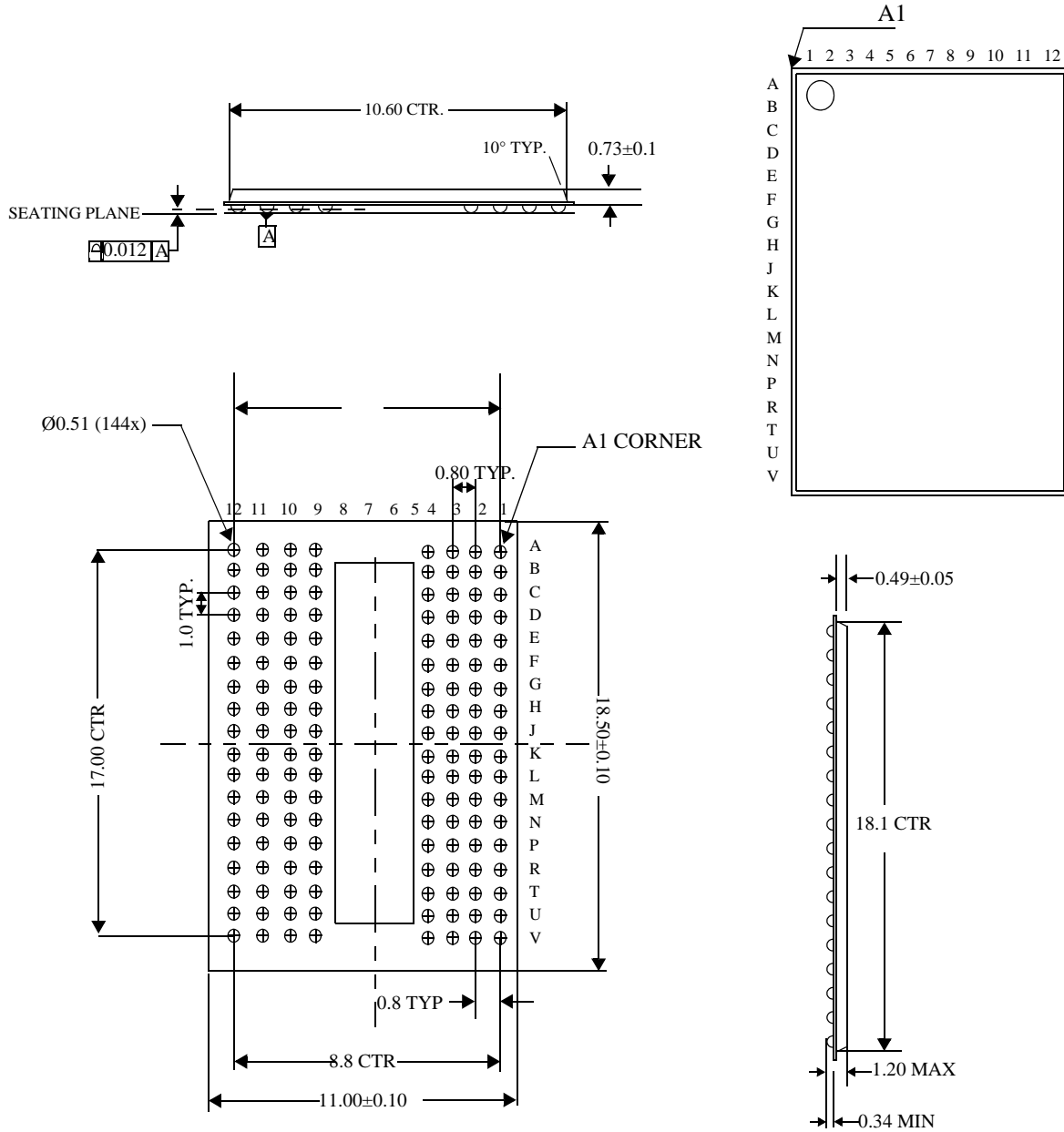


144-Bump μ BGA DummyDie™ Daisy Chain Package

Description

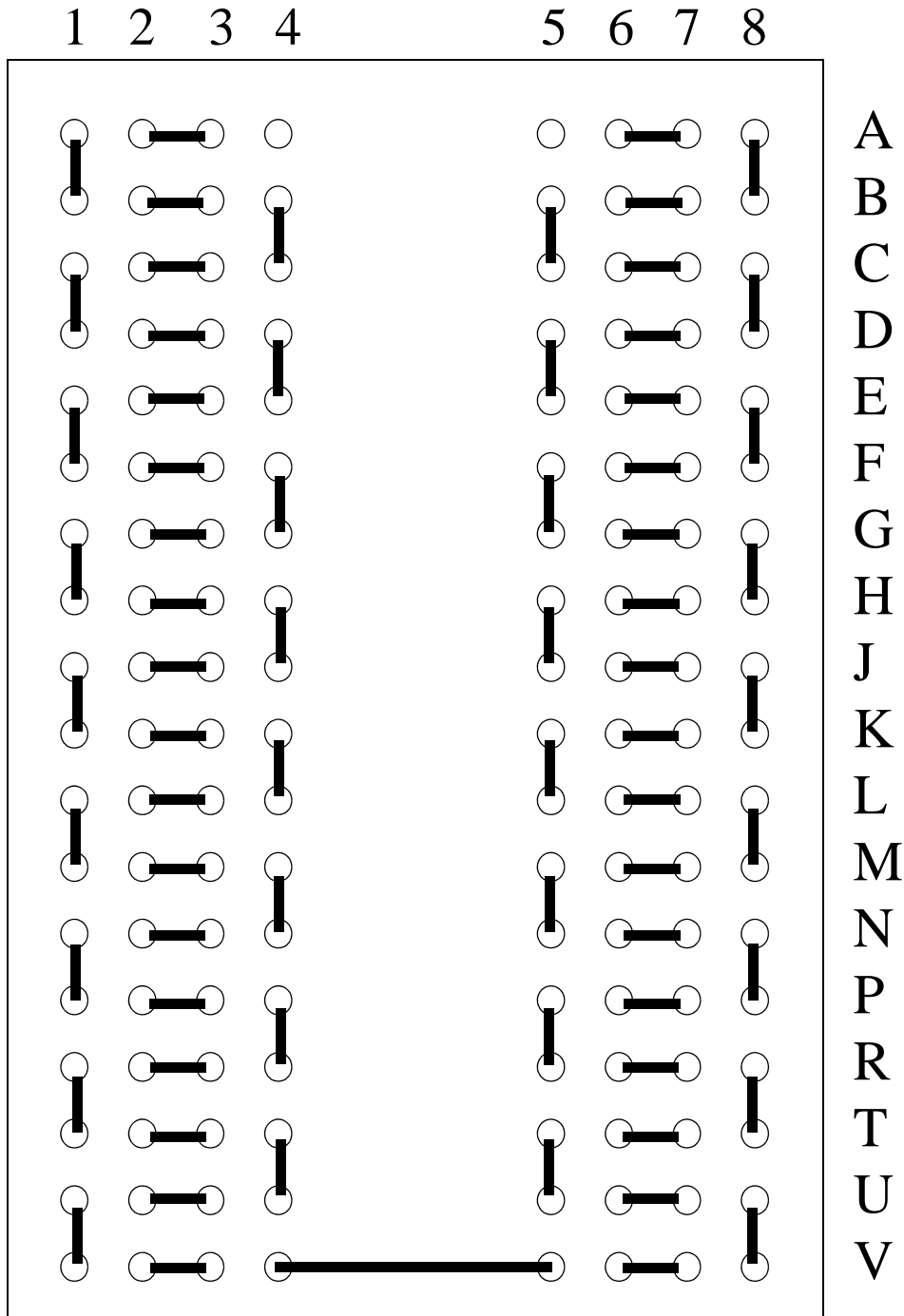
This mechanical daisy chain test vehicle is designed to represent the 144-Bump μ BGA package. It is used for second level interconnect assembly test and continuity verification. The DummyDie™ incorporates a 6.541 mm x 17.462 mm x 0.28 mm die, which is not electrically connected.

Package Dimensions—144-Bump μ BGA (Package L)



Note: All dimensions in millimeters.

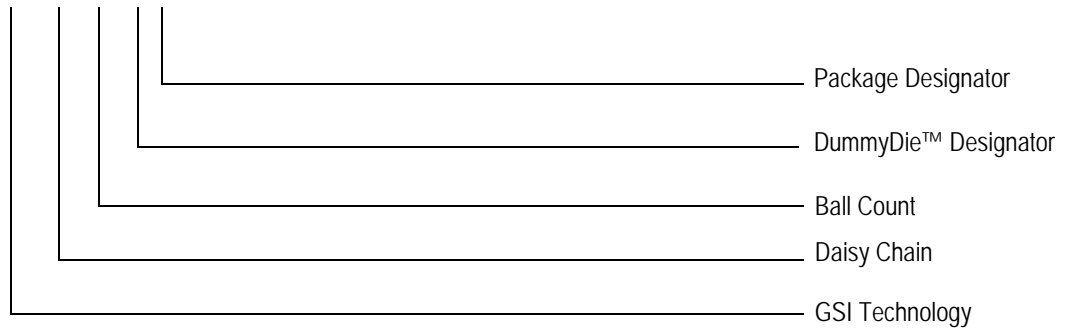
144-Bump μ BGA Interconnection Diagram (Package L)



Ordering Information

144-Bump μ BGA
Daisy Chain Package

GSDC144DL



144-Bump μ BGA
Daisy Chain Package
RoHS-compliant Option

GSDC144DGL

